

## Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output **DACs with Internal Reference and SPI Interface**

### **General Description**

**♦ Two High-Accuracy DAC Channels ♦ Monotonic Over All Operating Conditions** 

The MAX5700/MAX5701/MAX5702 2-channel, low-power, 8-/10-/12-bit, voltage-output digital-to-analog converters (DACs) include output buffers and an internal reference that is selectable to be 2.048V, 2.500V, or 4.096V. The MAX5700/MAX5701/MAX5702 accept a wide supply voltage range of 2.7V to 5.5V with extremely low power (1.5mW) consumption to accommodate most low-voltage applications. A precision external reference input allows rail-to-rail operation and presents a  $100k\Omega$  (typ) load to an external reference.

The MAX5700/MAX5701/MAX5702 have an a 50MHz 3-wire SPI/QSPI™/MICROWIRE®/DSP-compatible serial interface. The DAC output is buffered and has a low supply current of less than 250µA per channel and a low offset error of ±0.5mV (typ). On power-up, the MAX5700/MAX5701/ MAX5702 reset the DAC outputs to zero, providing additional safety for applications that drive valves or other transducers which need to be off on power-up. The internal reference is initially powered down to allow use of an external reference. The MAX5700/MAX5701/MAX5702 allow simultaneous output updates using software LOAD commands.

A clear logic input (CLR) allows the contents of the CODE and the DAC registers to be cleared asynchronously and sets the DAC outputs to zero. The MAX5700/MAX5701/ MAX5702 are available in a 10-pin µMAX® and an ultrasmall, 10-pin TDFN package and are specified over the -40°C to +125°C temperature range.

## **Applications**

Programmable Voltage and Current Sources Gain and Offset Adjustment Automatic Tuning and Optical Control Power Amplifier Control and Biasing Process Control and Servo Loops Portable Instrumentation **Data Acquisition** 

#### Ordering Information appears at end of data sheet.

QSPI is a trademark of Motorola, Inc. MICROWIRE is a registered trademark of National Semiconductor Corporation.

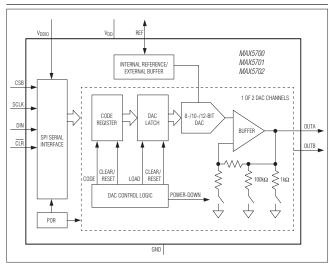
μΜΑΧ is a registered trademark of Maxim Integrated Products, Inc.

♦ Independent Mode Settings for Each DAC

**Benefits and Features** 

- **♦ Three Precision Selectable Internal References** ♦ 2.048V, 2.500V, or 4.096V
- ♦ Internal Output Buffer
  - ♦ Rail-to-Rail Operation with External Reference
  - ♦ 4.5µs Settling Time
  - ♦ Outputs Directly Drive 2kΩ Loads
- ♦ Small 5mm x 3mm 10-Pin µMAX or Ultra-Small 3mm x 3mm 10-Pin TDFN Package
- ♦ Wide 2.7V to 5.5V Supply Range
- ♦ Separate 1.8V to 5.5V V<sub>DDIO</sub> Power-Supply Input
- ♦ 50MHz 3-Wire SPI/QSPI/MICROWIRE/DSP Compatible Serial Interface
- ♦ Power-On-Reset to Zero-Scale DAC Output
- **♦** CLR For Asynchronous Control
- ♦ Three Software-Selectable Power-Down Output **Impedances** 
  - $\diamond$  1k $\Omega$ , 100k $\Omega$ , or High Impedance
- ♦ Low 350µA Supply Current at 3V VDD

## **Functional Diagram**



For related parts and recommended products to use with this part, refer to: www.maximintegrated.com/MAX5700.related

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maximintegrated.com.

## Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

### **ABSOLUTE MAXIMUM RATINGS**

V <sub>DD</sub> , V <sub>DDIO</sub> to GND0.3V to +6V	Maximum Continuous Current into Any Pin ±50mA
OUT_, REF to GND0.3V to the lower of $(V_{DD} + 0.3V)$ and +6V	Operating Temperature Range40°C to +125°C
CSB, SCLK, CLR to GND	Storage Temperature Range65°C to +150°C
DIN to GND0.3V to the lower of	Lead Temperature (soldering, 10s)+300°C
$(V_{DDIO} + 0.3V)$ and +6V	Soldering Temperature (reflow) +260°C
Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )	
μMAX (derate at 8.8mW/°C above 70°C)707mW TDFN (derate at 24.4mW/°C above 70°C)1951mW	
(	

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### PACKAGE THERMAL CHARACTERISTICS (Note 1)

μΜΑΧ	TDFN
Junction-to-Ambient Thermal Resistance (θJA)113°C/W	Junction-to-Ambient Thermal Resistance (θ <sub>JA</sub> )41°C/W
Junction-to-Case Thermal Resistance (θ <sub>JC</sub> )42°C/W	Junction-to-Case Thermal Resistance ( $\theta_{JC}$ )9°C/W

**Note 1:** Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to <a href="https://www.maximintegrated.com/thermal-tutorial">www.maximintegrated.com/thermal-tutorial</a>.

### **ELECTRICAL CHARACTERISTICS**

 $(V_{DD}=2.7V~to~5.5V,~V_{DDIO}=1.8V~to~5.5V,~V_{GND}=0V,~C_L=200pF,~R_L=2k\Omega,~T_A=-40^{\circ}C~to~+125^{\circ}C,~unless~otherwise~noted.~Typical~values~are~at~T_A=+25^{\circ}C.)~(Note~2)$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS			
DC PERFORMANCE (Note 3)									
		MAX5700	8						
Resolution and Monotonicity	N	MAX5701	10			Bits			
		MAX5702	12						
		MAX5700	-0.25	±0.05	+0.25				
Integral Nonlinearity (Note 4)	INL	MAX5701	-0.5	±0.25	+0.5	LSB			
		MAX5702	-1	±0.5	+1				
	DNL	MAX5700	-0.25	±0.05	+0.25				
Differential Nonlinearity (Note 4)		MAX5701	-0.5	±0.1	+0.5	LSB			
		MAX5702	-1	±0.2	+1				
Offset Error (Note 5)	OE		-5	±0.5	+5	mV			
Offset Error Drift				±10		μV/°C			
Gain Error (Note 5)	GE		-1.0	±0.1	+1.0	%FS			
Gain Temperature Coefficient		With respect to V <sub>REF</sub>		±3.0		ppm of FS/°C			
Zero-Scale Error			0		10	mV			
Full-Scale Error		With respect to V <sub>REF</sub>	-0.5		+0.5	%FS			

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### **ELECTRICAL CHARACTERISTICS (continued)**

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PARAMETER	SYMBOL	CON	NDITIONS	MIN	TYP	MAX	UNITS
DAC OUTPUT CHARACTERISTI	cs						
		No load		0		$V_{DD}$	
Output Voltage Range (Note 6)		$2k\Omega$ load to GND		0		V <sub>DD</sub> - 0.2	V
		$2k\Omega$ load to $V_{DD}$		0.2		$V_{DD}$	
Land Danielation		V /0	$V_{DD} = 3V \pm 10\%,$ $II_{OUT}I \le 5mA$		300		. ) // ^
Load Regulation		$V_{OUT} = V_{FS}/2$	$V_{DD} = 5V \pm 10\%,$ $II_{OUT}I \le 10mA$		300		μV/mA
DC Outrant leave adense		V /0	$V_{DD} = 3V \pm 10\%,$ $II_{OUT}I \le 5mA$		0.3		Ω
DC Output Impedance		$V_{OUT} = V_{FS}/2$	$V_{DD} = 5V \pm 10\%,$ $II_{OUT}I \le 10mA$		0.3		\$2
Maximum Capacitive Load Handling	CL				500		рF
Resistive Load Handling	RL			2			kΩ
Short-Circuit Output Current		V <sub>DD</sub> = 5.5V	Sourcing (output shorted to GND)		30		mA
Short-Circuit Output Current		VDD = 3.3V	Sinking (output shorted to V <sub>DD</sub> )	50			IIIA
DC Power-Supply Rejection		$V_{DD} = 3V \pm 10\%$ or	5V ±10%		100		μV/V
DYNAMIC PERFORMANCE	1						
Voltage-Output Slew Rate	SR	Positive and negati	ve		1.0		V/µs
		1/4 scale to 3/4 scale	, to ≤ 1 LSB, MAX5700		2.2		
Voltage-Output Settling Time		1/4 scale to 3/4 scale	, to ≤ 1 LSB, MAX5701		2.6		μs
		1/4 scale to 3/4 scale	, to ≤ 1 LSB, MAX5702		4.5		
DAC Glitch Impulse		Major code transition	on		7		nV*s
Channel-to-Channel		External reference		3.5			
Feedthrough (Note 7)		Internal reference		3.3		nV*s	
Digital Feedthrough		Code = 0, all digita		0.2		nV*s	
Power-Up Time		Startup calibration time (Note 8)			200		μs
I ower-op time		From power-down					μs

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### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{DD}=2.7V\ to\ 5.5V,\ V_{DDIO}=1.8V\ to\ 5.5V,\ V_{GND}=0V,\ C_L=200pF,\ R_L=2k\Omega,\ T_A=-40^{\circ}C\ to\ +125^{\circ}C,\ unless\ otherwise\ noted.$  Typical values are at  $T_A=+25^{\circ}C.)$  (Note 2)

PARAMETER	SYMBOL	CON	DITIONS	MIN	TYP	MAX	UNITS	
		F 1 1 1 1	f = 1kHz		90			
		External reference	f = 10kHz		82			
		2.048V internal	f = 1kHz		112			
Output Voltage-Noise Density		reference	f = 10kHz		102		->///	
(DAC Output at Midscale)		2.5V internal	f = 1kHz		125		nV/√Hz	
		reference	f = 10kHz		110			
		4.096V internal	f = 1kHz		160			
		reference	f = 10kHz		145			
			f = 0.1Hz to 10Hz		12			
		External reference	f = 0.1Hz to $10kHz$		76			
			f = 0.1Hz to 300kHz		385			
		0.0401/1	f = 0.1Hz to 10Hz		14			
		2.048V internal reference	f = 0.1Hz to $10kHz$		91			
Integrated Output Noise		reference	f = 0.1Hz to 300kHz		450			
(DAC Output at Midscale)		0.5)/: .	f = 0.1Hz to 10Hz		15		μV <sub>P-P</sub>	
		2.5V internal reference	f = 0.1Hz to $10kHz$		99			
		reference	f = 0.1Hz to 300kHz		470			
		4.0001/11	f = 0.1Hz to 10Hz		16			
		4.096V internal reference	f = 0.1Hz to $10kHz$		124			
		reference	f = 0.1Hz to 300kHz		490			
		External reference	f = 1kHz		114			
		External reference	f = 10kHz		99		nV/√Hz	
		2.048V internal	f = 1kHz		175			
Output Voltage-Noise Density		reference	f = 10kHz		153			
(DAC Output at Full Scale)		2.5V internal	f = 1kHz		200			
		reference	f = 10kHz		174			
		4.096V internal	f = 1kHz		295			
		reference	f = 10kHz		255			
			f = 0.1Hz to 10Hz		13			
		External reference	f = 0.1Hz to $10kHz$		94			
			f = 0.1Hz to 300kHz		540			
		0.040\/:	f = 0.1Hz to 10Hz		19			
		2.048V internal reference	f = 0.1Hz to $10kHz$		143			
Integrated Output Noise		reference	f = 0.1Hz to 300kHz		685		/	
(DAC Output at Full Scale)		0.51/:	f = 0.1Hz to 10Hz		21		μV <sub>P-P</sub>	
		2.5V internal	f = 0.1Hz to $10kHz$		159			
		reference	f = 0.1Hz to 300kHz		705			
		4.096V internal	f = 0.1Hz to 10Hz		26			
			f = 0.1Hz to $10kHz$		213			
		reference	f = 0.1Hz to 300kHz		750			

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### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{DD}=2.7V\ to\ 5.5V,\ V_{DDIO}=1.8V\ to\ 5.5V,\ V_{GND}=0V,\ C_L=200pF,\ R_L=2k\Omega,\ T_A=-40^{\circ}C\ to\ +125^{\circ}C,\ unless\ otherwise\ noted.$  Typical values are at  $T_A=+25^{\circ}C.)$  (Note 2)

PARAMETER	SYMBOL	COI	NDITIONS	MIN	TYP	MAX	UNITS	
REFERENCE INPUT								
Reference Input Range	V <sub>REF</sub>			1.24		V <sub>DD</sub>	V	
Reference Input Current	I <sub>REF</sub>	$V_{REF} = V_{DD} = 5.5V$	/		55	74	μA	
Reference Input Impedance	R <sub>REF</sub>			75	100		kΩ	
REFERENCE OUPUT								
		$V_{REF} = 2.048V, T_{A}$	= +25°C	2.043	2.048	2.053		
Reference Output Voltage	V <sub>REF</sub>	V <sub>REF</sub> = 2.5V, T <sub>A</sub> =	+25°C	2.494	2.500	2.506	V	
		$V_{REF} = 4.096V, T_{A}$	4.086	4.096	4.106	1		
			f = 1kHz		129			
		$V_{REF} = 2.048V$	f = 10kHz		122			
5.6		.,	f = 1kHz		158		] ,,, <u>,</u>	
Reference Output Noise Density		$V_{REF} = 2.500V$	f = 10kHz		151	nV/√H		
		.,	f = 1kHz		254			
		V <sub>REF</sub> = 4.096V	f = 10kHz		237		1	
			f = 0.1Hz to 10Hz		12			
		$V_{REF} = 2.048V$	f = 0.1Hz to $10kHz$		110		1	
			f = 0.1Hz to 300kHz		390			
			f = 0.1Hz to 10Hz		15			
Integrated Reference Output Noise		$V_{REF} = 2.500V$	f = 0.1Hz to $10kHz$		129		μν <sub>Ρ-Ρ</sub>	
Noise			f = 0.1Hz to 300kHz		430			
			f = 0.1Hz to 10Hz		20		1	
		$V_{REF} = 4.096V$	f = 0.1Hz to $10kHz$		205		7	
			f = 0.1Hz to 300kHz		525			
Reference Temperature		MAX5702A			±3	±10		
Coefficient (Note 9)		MAX5700/MAX570	1/MAX5702B		±10	±25	ppm/°C	
Reference Drive Capacity		External load			25		kΩ	
Reference Capacitive Load					200		pF	
Reference Load Regulation		I <sub>SOURCE</sub> = 0 to 500µA			2		mV/mA	
Reference Line Regulation	Reference Line Regulation						mV/V	
POWER REQUIREMENTS				,				
Supply Voltage	Voo	V <sub>REF</sub> = 4.096V		4.5		5.5	V	
Supply Vollage	$V_{DD}$	All other options	2.7		5.5	V		
I/O Supply Voltage	V <sub>DDIO</sub>		1.8		5.5	V		

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### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{DD}=2.7V\ to\ 5.5V,\ V_{DDIO}=1.8V\ to\ 5.5V,\ V_{GND}=0V,\ C_L=200pF,\ R_L=2k\Omega,\ T_A=-40^{\circ}C\ to\ +125^{\circ}C,\ unless\ otherwise\ noted.$  Typical values are at  $T_A=+25^{\circ}C.)$  (Note 2)

PARAMETER	SYMBOL	CON	DITIONS	MIN	TYP	MAX	UNITS
			V <sub>REF</sub> = 2.048V		0.55	0.75	
		Internal reference	$V_{REF} = 2.5V$		0.60	0.80	
Supply Current (Note 10)	I <sub>DD</sub>		$V_{REF} = 4.096V$		0.65	0.90	mA
		External reference	V <sub>REF</sub> = 3V		0.40	0.60	
		External reference	$V_{REF} = 5V$		0.55	0.75	
Interface Supply Current (Note 10)	I <sub>DDIO</sub>					1	μΑ
		All DACs off, interna	Il reference ON		140		
Power-Down Mode Supply	I <sub>PD</sub>	All DACs off, internation $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$			0.5	1	μΑ
Current		All DACs off, internal T <sub>A</sub> = +125°C		1.2	2.5		
DIGITAL INPUT CHRACTERIST	CS (CSB, SC	CLK, DIN, CLR)					
Hysteresis Voltage	V <sub>H</sub>				0.15		V
Innert High Veltage	N/	2.2V < V <sub>DDIO</sub> < 5.5\	/	0.7x V <sub>DDIO</sub>			V
Input High Voltage	V <sub>IH</sub>	1.8V < V <sub>DDIO</sub> < 2.2\	/	0.8x V <sub>DDIO</sub>			V
	.,	2.2V < V <sub>DDIO</sub> < 5.5\			0.3 x V <sub>DDIO</sub>	.,	
Input Low Voltage	V <sub>IL</sub>	1.8V < V <sub>DDIO</sub> < 2.2\			0.2 x V <sub>DDIO</sub>	V	
Input Leakage Current	I <sub>IN</sub>	$V_{IN} = 0V \text{ or } V_{DDIO}$ (I	Note 10)		±0.1	±1	μΑ
Input Capacitance (Note 10)	C <sub>IN</sub>					10	рF
SPI TIMING CHARACTERISTICS	(CSB, SCLI	K, DIN, CLR) (Note 11	1)				
SCLK Frequency	facus	2.7V < V <sub>DDIO</sub> < 5.5\	/			50	MHz
SOLIN Frequency	†SCLK	1.8V < V <sub>DDIO</sub> < 2.7\	/			33	IVII IZ
SCLK Period	toour	2.7V < V <sub>DDIO</sub> < 5.5\	/	20			ns
SOLIVI GIIOU	<sup>t</sup> SCLK	1.8V < V <sub>DDIO</sub> < 2.7\	/	30			115
SCLK Pulse Width High	t <sub>CH</sub>			8			ns
SCLK Pulse Width Low	t <sub>CL</sub>			8			ns
CSB Fall to SCLK Fall Setup Time	t <sub>CSS0</sub>	To first SCLK falling	edge	8			ns
CSB Fall to SCLK Fall Hold Time	t <sub>CSH0</sub>	Applies to inactive Spreceding the first S		0			ns
CSB Rise to SCLK Fall Hold Time	t <sub>CSH1</sub>	Applies to the 24th	SCLK falling edge	0			ns

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### **ELECTRICAL CHARACTERISTICS (continued)**

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PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
CSB Rise to SCLK Fall	t <sub>CSA</sub>	Applies to the 24th SCLK falling edge, aborted sequence	12			ns
SCLK Fall to CSB Fall	t <sub>CSF</sub>	Applies to 24th SCLK falling edge	100			ns
CSB Pulse Width High	t <sub>CSPW</sub>		20			ns
DIN to SCLK Fall Setup Time	t <sub>DS</sub>		5			ns
DIN to SCLK Fall Hold Time	t <sub>DH</sub>		4.5			ns
CLR Pulse Width Low	t <sub>CLPW</sub>		20			ns
CLR Rise to CSB Fall	t <sub>CSC</sub>	Required for command to be executed	20			ns

- **Note 2:** Limits are 100% production tested at T<sub>A</sub> = +25°C and/or T<sub>A</sub> = +125°C. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization. Typical values are at T<sub>A</sub> = +25°C and are not guaranteed.
- Note 3: DC Performance is tested without load.
- **Note 4:** Linearity is tested with unloaded outputs to within 20mV of GND and V<sub>DD</sub>.
- **Note 5:** Offset and gain calculated from measurements made with  $V_{REF} = V_{DD}$  at code 30 and 4065 for MAX5702, code 8 and 1016 for MAX5701, and code 2 and 254 for MAX5700.
- **Note 6:** Subject to zero and full-scale error limits and V<sub>RFF</sub> settings.
- Note 7: Measured with all other DAC outputs at midscale with one channel transitioning 0 to full scale.
- Note 8: On power-up, the device initiates an internal 200µs (typ) calibration sequence. All commands issued during this time will be ignored.
- Note 9: Guaranteed by design.
- Note 10: All channels active at V<sub>FS</sub>, unloaded. Static logic inputs with V<sub>IL</sub> = V<sub>GND</sub> and V<sub>IH</sub> = V<sub>DDIO</sub>.
- **Note 11:** All timing tested with  $V_{IL} = V_{GND}$  and  $V_{IH} = V_{DDIO}$ .

# Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

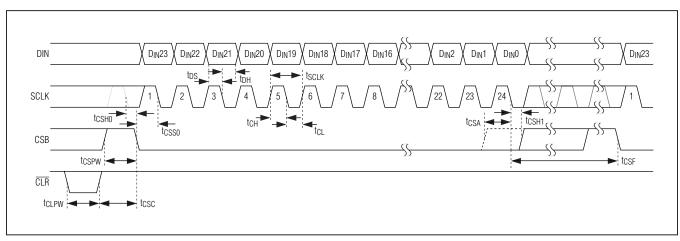
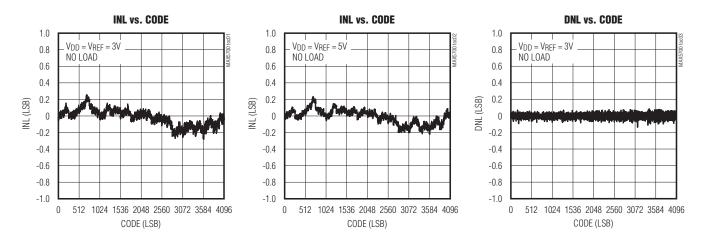


Figure 1. SPI Serial Interface Timing Diagram

### **Typical Operating Characteristics**

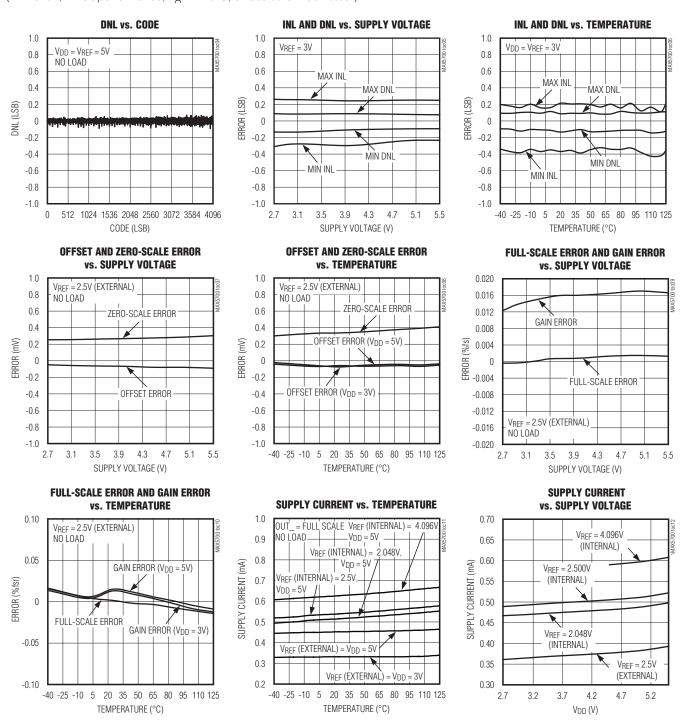
(MAX5702, 12-bit performance,  $T_A = +25$ °C, unless otherwise noted.)



# Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

Typical Operating Characteristics (continued)

(MAX5702, 12-bit performance,  $T_A = +25$ °C, unless otherwise noted.)

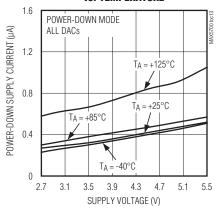


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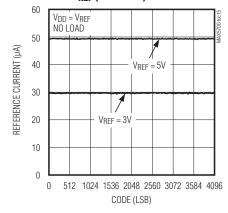
## Typical Operating Characteristics (continued)

(MAX5702, 12-bit performance, TA = +25°C, unless otherwise noted.)

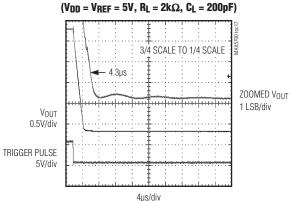




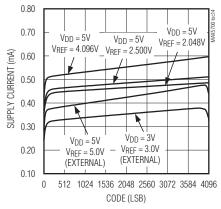




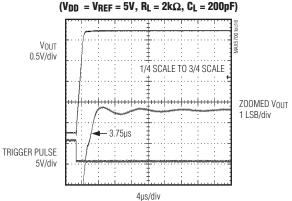
SETTLING TO ±1 LSB



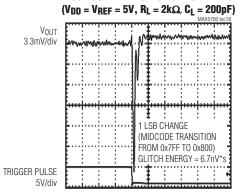
### SUPPLY CURRENT vs. CODE



SETTLING TO ±1 LSB



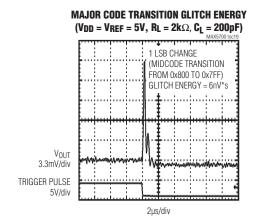
**MAJOR CODE TRANSITION GLITCH ENERGY** 

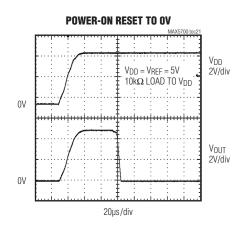


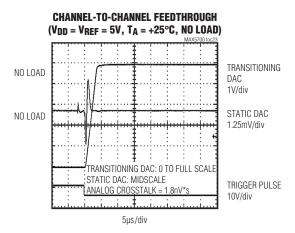
# Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

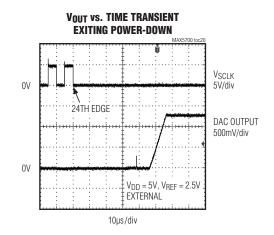
Typical Operating Characteristics (continued)

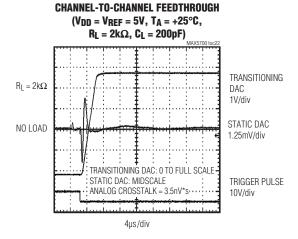
(MAX5702, 12-bit performance,  $T_A = +25^{\circ}C$ , unless otherwise noted.)

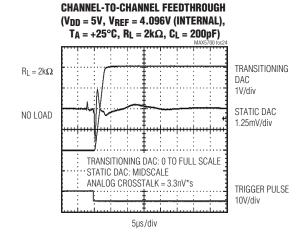








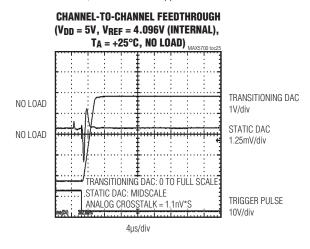


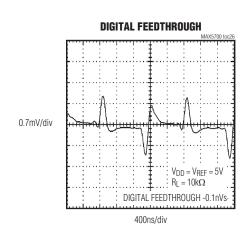


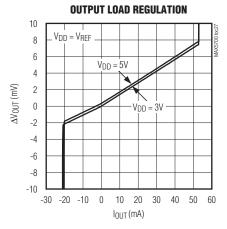
# Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

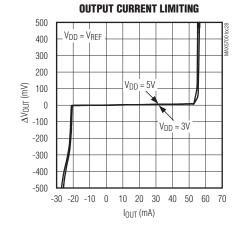
Typical Operating Characteristics (continued)

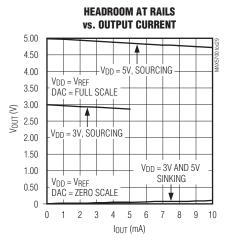
(MAX5702, 12-bit performance,  $T_A = +25$ °C, unless otherwise noted.)

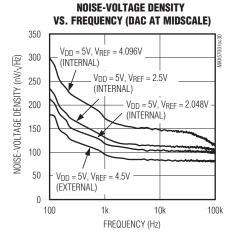










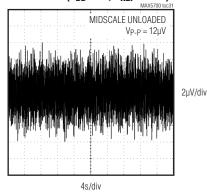


# Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

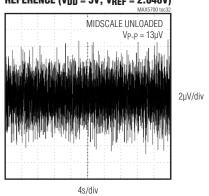
**Typical Operating Characteristics (continued)** 

(MAX5702, 12-bit performance,  $T_A = +25^{\circ}C$ , unless otherwise noted.)

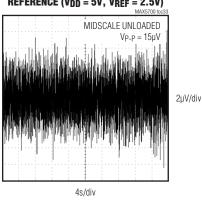
## 0.1Hz TO 10Hz OUTPUT NOISE, EXTERNAL REFERENCE (VDD = 5V, VREF = 4.5V)



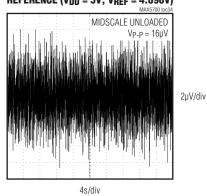
## 0.1Hz TO 10Hz OUTPUT NOISE, INTERNAL REFERENCE ( $V_{DD} = 5V$ , $V_{REF} = 2.048V$ )



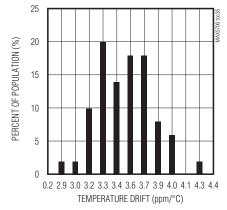
## 0.1Hz TO 10Hz OUTPUT NOISE, INTERNAL REFERENCE (VDD = 5V, VREF = 2.5V)



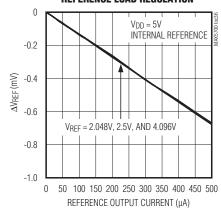
## 0.1Hz TO 10Hz OUTPUT NOISE, INTERNAL REFERENCE (VDD = 5V, VREF = 4.096V)



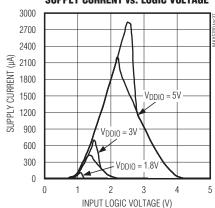
#### **VREF DRIFT VS. TEMPERATURE**



### REFERENCE LOAD REGULATION

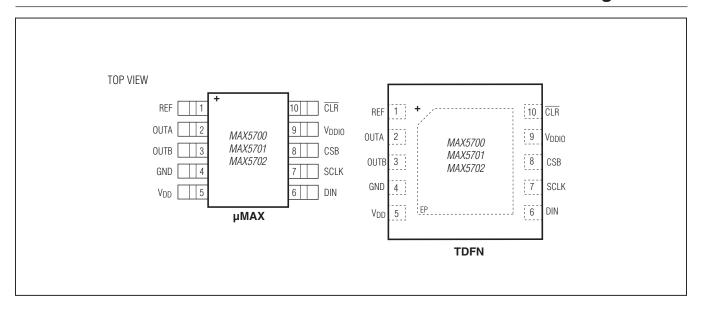


#### SUPPLY CURRENT vs. LOGIC VOLTAGE



# Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

**Pin Configurations** 



## **Pin Description**

PIN	NAME	FUNCTION
1	REF	Reference Voltage Input/Output
2	OUTA	Buffered Channel A DAC Output
3	OUTB	Buffered Channel B DAC Output
4	GND	Ground
5	V <sub>DD</sub>	Supply Voltage Input. Bypass V <sub>DD</sub> with at least a 0.1µF capacitor to GND.
6	DIN	SPI Interface Data Input
7	SCLK	SPI Interface Clock Input
8	CSB	SPI Chip-Select Input
9	V <sub>DDIO</sub>	Digital Interface Power-Supply Input
10	CLR	Active-Low Clear Input
_	EP	Exposed Pad (TDFN Only). Connect to ground.

# Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

### **Detailed Description**

The MAX5700/MAX5701/MAX5702 are 2-channel, lowpower, 8-/10-/12-bit buffered voltage-output DACs. The 2.7V to 5.5V wide supply voltage range and low-power consumption accommodates most low-power and lowvoltage applications. The devices present a  $100k\Omega$  load to the external reference. The internal output buffers allow rail-to-rail operation. An internal voltage reference is available with software selectable options of 2.048V, 2.5V, or 4.096V. The devices feature a 50MHz, 3-wire SPI/QSPI/MICROWIRE/DSP-compatible serial interface to save board space and reduce the complexity in isolated applications. The MAX5700/MAX5701/MAX5702 include a serial-in/parallel-out shift register, internal CODE and DAC registers, a power-on-reset (POR) circuit to initialize the DAC outputs to code zero, and control logic. CLR is available to asynchronously clear the device independent of the serial interface.

### DAC Outputs (OUT\_)

The MAX5700/MAX5701/MAX5702 include internal buffers on all DAC outputs. The internal output buffers provide improved load regulation for the DAC outputs. The output buffers slew at 1V/µs (typ) and drive resistive loads as low as  $2k\Omega$  in parallel with as much as 500pF of capacitance.. The analog supply voltage (VDD) determines the maximum output voltage range of the devices as VDD powers the output buffer. Under no-load conditions, the output buffers drive from GND to VDD, subject to offset and gain errors. With a  $2k\Omega$  load to GND, the output buffers drive from GND to within 200mV of VDD. With a  $2k\Omega$  load to VDD, the output buffers drive from VDD to within 200mV of GND.

The DAC ideal output voltage is defined by:

$$V_{OUT} = V_{REF} \times \frac{D}{2^N}$$

where D = code loaded into the DAC register,  $V_{REF} = \text{reference voltage}$ , N = resolution.

#### **Internal Register Structure**

The user interface is separated from the DAC logic to minimize digital feedthrough. Within the serial interface is an input shift register, the contents of which can be routed to control registers, individual, or multiple DACs as determined by the user command.

Within each DAC channel there is a CODE register followed by a DAC latch register (see the *Detailed* 

Functional Diagram). The contents of the CODE register hold pending DAC output settings which can later be loaded into the DAC registers. The CODE register can be updated using both CODE and CODE\_LOAD user commands. The contents of the DAC register hold the current DAC output settings. The DAC register can be updated directly from the serial interface using the CODE\_LOAD commands or can upload the current contents of the CODE register using LOAD commands.

The contents of both CODE and DAC registers are maintained during power-down states, so that when the DACs are powered on, they return to their previously stored output settings. Any CODE or LOAD commands issued during power-down states continue to update the register contents. SW\_CLEAR and SW\_RESET commands reset the contents of all CODE and DAC registers to their zero-scale defaults.

#### **Internal Reference**

The MAX5700/MAX5701/MAX5702 include an internal precision voltage reference that is software selectable to be 2.048V, 2.500V, or 4.096V. When an internal reference is selected, that voltage is available on the REF pin for other external circuitry (see the Typical Operating Circuits) and can drive a 25k $\Omega$  load.

### **External Reference**

The external reference input has a typical input impedance of  $100k\Omega$  and accepts an input voltage from +1.24V to  $V_{DD}$ . Connect an external voltage supply between REF and GND to apply an external reference. The MAX5700/MAX5701/MAX5702 power up and reset to external reference mode. Visit www.maximintegrated.com/products/references for a list of available external voltage-reference devices.

#### Clear Input (CLR)

The MAX5700/MAX5701/MAX5702 feature an asynchronous active-low  $\overline{\text{CLR}}$  logic input that simultaneously sets both DAC outputs to zero. Driving  $\overline{\text{CLR}}$  low clears the contents of both the CODE and DAC registers and also aborts the on-going SPI command. To allow a new SPI command, drive  $\overline{\text{CLR}}$  high, satisfying the t<sub>CSC</sub> timing requirement.

#### Interface Power Supply (VDDIO)

The MAX5700/MAX5701/MAX5702 feature a separate supply pin ( $V_{\rm DDIO}$ ) for the digital interface (1.8V to 5.5V). Connect  $V_{\rm DDIO}$  to the I/O supply of the host processor.

## Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

#### SPI Serial Interface

The MAX5700/MAX5701/MAX5702 3-wire serial interface is compatible with MICROWIRE, SPI, QSPI, and DSPs. The interface provides three inputs, SCLK, CSB, and DIN. The chip-select input (CSB, active low) frames the data loaded through the serial data input (DIN). Following a CSB input high-to-low transition, the data is shifted in synchronously and latched into the input register on each falling edge of the serial clock input (SCLK). Each serial operation word is 24-bits long. The DAC data is left justified as shown in Table 1. The serial input register transfers its contents to the destination registers after loading 24 bits of data on the 24th SCLK falling edge. To initiate a new SPI operation, drive CSB high and then low to begin the next operation sequence, being sure to meet all relevant timing requirements. During CSB high periods, SCLK is ignored, allowing communication to other devices on the same bus. SPI operations consisting of more than 24 SCLK cycles are executed on the 24th SCLK falling edge, using the first three bytes of data available. SPI operations consisting of less than 24 SCLK cycles will not be executed. The content of the SPI operation consists of a command byte followed by a two byte data word.

Figure 1 shows the timing diagram for the complete 3-wire serial interface transmission. The DAC code settings (D) for the MAX5700/MAX5701/MAX5702 are accepted in an offset binary format (see <u>Table 1</u>). Otherwise, the expected data format for each command is listed in <u>Table 2</u>. See Figure 2 for an example of a typical SPI circuit application.

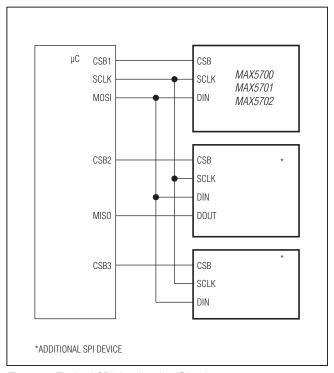


Figure 2. Typical SPI Application Circuit

#### **SPI User-Command Register Map**

This section lists the user accessible commands and registers for the MAX5700/MAX5701/MAX5702.

<u>Table 2</u> provides detailed information about the Command Registers.

Table	1	Format	DAC	Data	Rit	<b>Positions</b>
Iaure		CULITAL		11010		FUSITIONS.

PART	B15	B14	B13	B12	B11	B10	В9	В8	В7	В6	B5	B4	В3	B2	B1	В0
MAX5700	D7	D6	D5	D4	D3	D2	D1	D0	Х	Х	Х	Х	Х	Х	Х	Х
MAX5701	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	Х	Х	Х	Х	Х	Х
MAX5702	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	Х	Х	Х	Х

# Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

	DESCRIPTION		Writes data to the selected CODE register(s)	Transfers data from the selected CODE register(s) to the selected DAC register(s)	Simultaneously writes data to the selected CODE register(s) while updating all DAC registers	Simultaneously writes data to the selected CODE register(s) while updating selected DAC register(s)		Sets the power mode of the selected DACs (DACs selected with a 1 in the corresponding DACn bit are updated, DACs with a 0 in the corresponding DACn bit are not impacted)	Executes a software clear (all CODE and DAC registers cleared to their default values)	Executes a software reset (all CODE, DAC, and control registers returned to their default values)			
	B0		×	×	×	×		×	×	×			
	B1		×	×	×	×		×	×	×			
	B2		×	×	×	×		×	×	×			
	B3		×	×	×	×		×	×	×			
	<b>B</b> 4		TER	×	TER	TER		×	×	×			
	B2		DE REGIST DATA[3:0]	×	DE REGIST DATA[3:0]	DE REGIST DATA[3:0]		×	×	×			
	Be		CODE REGISTER DATA[3:0]	×	CODE REGISTER DATA[3:0]	CODE REGISTER DATA[3:0]		×	×	×			
	B7		8	×	00	8		×	×	×			
	B8			×				DACA	×	×			
	B9			×				DVCB	×	×			
	B10		EB _	×	ER _	H _		×	×	×			
	B11		CODE REGISTER DATA[11:4]	×	EGIST	EGIS <sup>-</sup> [11:4	CODE REGISTER DATA[11:4]		×	×	×		
	B12		DE RI	×	CODE REGISTER DATA[11:4]	DE RI		×	×	×			
	B13		00	×	8		8	8	8		×	×	×
	B14			×				×	×	×			
>	B15			×	×		×	×	×				
ds Summary	B16		N O	N C	NC	Z C		Ver de de mal PD PD KO	0	-			
Ш	B17		DAC SELECTION	DAC SELECTION	DAC SELECTION	DAC SELECTION		Power Mode 00 = 00 = Normal 01 = PD 14Ω 100 = PD 100 HZ 11 = PD 100 HZ 11 = PD Hi-Z	0	0			
S	9 B18 B17		SEL	SEL	SEL	SEL		0	0	0			
pu	<u>B</u>		DAC	DA(	DA(	DA(		0	0	0			
ıma	B20		0	τ-	0	-	ANDS	0	Τ-	-			
Om	B21		0	0	<del>-</del>	<del>-</del>	MMC	0	0	0			
0	B23 B22 B21	SC	0	0	0	0	S N	+	Ψ-	-			
S	B23	MANI	0	0	0	0	NATI(	0	0	0			
Table 2. SPI Comman	COMMAND	DAC COMMANDS	CODEn	LOADn	CODEn_ LOAD_ALL	CODEn_ LOADn	CONFIGURATION COMMANDS	POWER	SW_CLEAR	SW_RESET			

# Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

									,															
COMMAND B23 B22 B21 B20 B1	B23	B22	B21	B20	B19	B18	B17	B16	B15	B14 B13	B13	B12 B11 B10	B11		B9	B8	B7	B6 I	B5 B	B4 B3	3 B2	E	B0	DESCRIPTION
CONFIG	0	<del>-</del>	<del>-</del>	0	0	0	0	<u> CD_EN</u>	×	×	×	×	×	×	DVC B	A DAC	×	×	^ ×	× ×	×	×	×	Sets the DAC Latch Mode of the selected DACs. Only DACS with a 1 in the selection bit are updated by the command.  \[ \overline{LD_EN} = 0: DAC latch \] is operational (LOAD controlled) \[ \overline{LD_EN} = 1: DAC latch \] transparent
ZE F	0	-	-	-	0	Paver Parer On 1 = 1	REF Mode 00 = EXT 01 = 2.5V 10 = 2.0V	REF Mode 00 = EXT 01 = 2.5V 10 = 2.0V 11 = 4.1V	×	×	×	×	×	×	×	×	×	×	×	×	×	×	×	Sets the reference operating mode. REF Power (B18): 0 = Internal reference is only powered if at least one DAC is powered 1 = Internal reference is always powered
ALL DAC COMMANDS	OMIN	IAND	SC								}	}												
CODE_ALL	-	0	0	0	0	0	0	0			100	CODE REGISTER DATA[11:4]	GISTI 11:4]	H			COD	DE REGIST DATA[3:0]	CODE REGISTER DATA[3:0]	× ×	×	×	×	Writes data to all CODE registers
LOAD_ALL	-	0	0	0	0	0	0	<del>-</del>	×	×	×	×	×	×	×	×	×	×	× ×	×	×	×	×	Updates all DAC latches with current CODE register data
CODE_ ALL_ LOAD_ALL	τ-	0	0	0	0	0	1	×				CODE REGISTER DATA[11:4]	GISTI 11:4]	ER			COD	DE REGIST DATA[3:0]	CODE REGISTER DATA[3:0]	×	×	×	×	Simultaneously writes data to all CODE registers while updating all DAC registers
NO OPERATION COMMANDS	VOIT	CO	MMA	NDS																				
	-	0	0	-	×	×	×	×	×	×	×	×	×	×	×	×	×	×	×	×	×	×	×	
No Operation	-	0	-	×	×	×	×	×	×	×	×	×	×	×	×	×	×	×	^ ×	×	×	×	×	These commands will have
	-	_	×	×	×	×	×	×	×	×	×	×	×	×	×	×	×	×	×	×	×	×	×	
Reserved Commands: Any commands not specifically listed above are reserved for Maxim internal use only	omm	ands	:: Any	, com	manc	ds not	speci	ifically	/ listed	d abov	ve are	ese (	rved f	or Ma	xim in	ternal	nse	only.						

Table 2. SPI Commands Summary (continued)

## Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

#### **CODEn Command**

The CODEn command (B[23:20] = 0000) updates the CODE register contents for the selected DAC(s). Changes to the CODE register content based on this command will not affect DAC outputs directly unless the DAC latch has been configured to be transparent. Issuing the CODEn command with DAC SELECTION = ALL DACs is equivalent to CODE\_ALL (B[23:16] = 10000000). See Table 2 and Table 3.

#### **LOADn Command**

The LOADn command (B[23:20] = 0001) updates the DAC register content for the selected DAC(s) by uploading the current contents of the CODE register. The LOADn command can be used with DAC SELECTION = ALL DACs to issue a software load for all DACs, which is equivalent to the LOAD\_ALL (B[23:16] = 10000001) command. See Table 2 and Table 3.

### CODEn\_LOAD\_ALL Command

The CODEn\_LOAD\_ALL command (B[23:20] = 0010) updates the CODE register contents for the selected DAC(s) as well as the DAC register content of all DACs. Channels for which the CODE register content has not been modified since the last load to DAC register operation will not be updated to reduce digital crosstalk. Issuing this command with DAC\_ADDRESS = ALL is equivalent to the CODE\_ALL\_LOAD\_ALL (B[23:16] = 1000001x) command. The CODEn\_LOAD\_ALL command by definition will modify at least one CODE register. To avoid this, use

the LOADn command with DAC SELECTION = ALL DACs or use the LOAD\_ALL command. See Table 2 and Table 3.

#### CODEn\_LOADn Command

The CODEn\_LOADn command (B[23:20] = 0011) updates the CODE register contents for the selected DAC(s) as well as the DAC register content of the selected DAC(s). Channels for which the CODE register content has not been modified since the last load to DAC register operation will not be updated to reduce digital crosstalk. Issuing this command with DAC SELECTION = ALL DACs is equivalent to the CODE\_ALL\_LOAD\_ALL command. See Table 2 and Table 3.

### **CODE ALL Command**

The CODE\_ALL command (B[23:16] = 10000000) updates the CODE register contents for all DACs. See Table 2.

#### **LOAD ALL Command**

The LOAD\_ALL command (B[23:16] = 10000001) updates the DAC register content for all DACs by uploading the current contents of the CODE registers. See Table 2.

### **CODE\_ALL\_LOAD\_ALL Command**

The CODE\_ALL\_LOAD\_ALL command (B[23:16] = 1000001x) updates the CODE register contents for all DACs as well as the DAC register content of all DACs. See Table 2.

Table 3. DAC Selection

B19	B18	B17	B16	DAC SELECTED
0	0	0	0	DAC A
0	0	0	1	DAC B
0	0	1	X	No effect
X	1	X	X	ALL DACs
1	X	Х	Х	ALL DACs

# Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

#### **POWER Command**

The MAX5700/MAX5701/MAX5702 feature a software-controlled power-mode (POWER) command (B[23:18] = 010000). The POWER command updates the power-mode settings of the selected DACs while the power settings of the rest of the DACs remain unchanged. The new power setting is determined by bits B[17:16] while the affected DAC(s) are selected by bits B[9:8]. If all DACs are powered down, the device enters a STANDBY mode.

In power-down, the DAC output is disconnected from the buffer and is grounded with either one of the two selectable internal resistors or set to high impedance. See <u>Table 5</u> for the selectable internal resistor values in power-down mode. In power-down mode, the DAC register retains its value so that the output is restored when the device powers up. The serial interface remains active in power-down mode.

In STANDBY mode, the internal reference can be powered down or it can be set to remain powered-on for external use. Also, in STANDBY mode, devices using the external reference do not load the REF pin. See Table 4.

#### SW RESET and SW CLEAR Command

The SW\_RESET (B[23:16] = 01010001) and SW\_CLEAR (B[23:16] = 01010000) commands provide a means of issuing a software reset or software clear operation. Use SW\_CLEAR to issue a software clear operation to return all CODE and DAC registers to the zero-scale value. Use SW\_RESET to reset all CODE, DAC, and configuration registers to their default values.

### **Table 4. POWER Command Format**

B23	B22	B21	B20	B19	B18	B17	B16	B15	B14	B13	B12	B11	B10	В9	В8	В7	В6	B5	В4	В3	B2	B1	В0
0	1	0	0	0	0	PD1	PD0	Χ	Χ	Χ	Χ	Χ	Χ	В	Α	Χ	Χ	Χ	Χ	Χ	Χ	Χ	Χ
	POV	VER (	Comm	nand		100	de: ) = mal			Don't	Care			Selection Selection Selection Selection Selection Number 1	tiple AC ction: DAC cted DAC ot				Don't	Care			
De	fault \	/alues	s (all [	DACs	) →	0	0	Χ	Х	Χ	Χ	Χ	Χ	1	1	Χ	Χ	Χ	Χ	Χ	Χ	Χ	Χ

### Table 5. Selectable DAC Output Impedance in Power-Down Mode

PD1 (B17)	PD0 (B16)	OPERATING MODE
0	0	Normal operation
0	1	Power-down with internal 1kΩ pulldown resistor to GND.
1	0	Power-down with internal $100k\Omega$ pulldown resistor to GND.
1	1	Power-down with high-impedance output.

## Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

#### **CONFIG Command**

The CONFIG command (B[23:17] = 0110000) updates the LOAD functions of selected DACs. Issue the command with B16 = 0 to allow the DAC latches to operate normally or with B16 = 1 to disable the DAC latches, making them perpetually transparent. Mode settings of the selected DACs are updated while the mode settings of the rest of the DACs remain unchanged; DAC(s) are selected by bits B[9:8]. See Table 6.

#### **REF Command**

The REF command updates the global reference setting used for all DAC channels. Set B[17:16] = 00 to use an external reference for the DACs or set B[17:16] to 01, 10, or 11 to select either the 2.5V, 2.048V, or 4.096V internal reference, respectively.

If RF2 (B18) is set to zero (default) in the REF command, the reference will be powered down any time all DAC channels are powered down (in STANDBY mode). If RF2 (B18 = 1) is set to one, the reference will remain powered even if all DAC channels are powered down, allowing continued operation of external circuitry. In this mode, the  $1\mu A$  shutdown state is not available. See Table 7.

### **Table 6. CONFIG Command Format**

B23	B22	B21	B20	B19	B18	B17	B16	B15	B14	B13	B12	B11	B10	В9	В8	В7	В6	B5	В4	В3	B2	B1	В0
0	1	1	0	0	0	0	LDB	Χ	Χ	Х	Χ	Χ	Χ	В	Α	Х	Х	Χ	Χ	Χ	Χ	Χ	Х
							٦t								tiple								
							- Normal ransparent								AC .								
							Jormal nspare				_				ction:					_			
	C	CONFI	G Cor	mman	d		. Nc			Don't	Care				DAC				Don't	Care			
							0 = = Tr								cted								
							1								AC Not								
														Sele	cted								
	Defau	It Valu	ues (a	all DA	Cs) —	•	0	Χ	Χ	Χ	Χ	Χ	Χ	1	1	Χ	Χ	Χ	Χ	Χ	Χ	Χ	Χ

### **Table 7. REF Command Format**

B23	B22	B21	B20	B19	B18	B17	B16	B15	B14	B13	B12	B11	B10	В9	B8	В7	В6	B5	В4	В3	B2	В1	В0
0	1	1	1	0	RF2	RF1	RF0	Χ	Х	Х	Х	Χ	Χ	Χ	Χ	Χ	Х	Χ	Х	Х	Χ	Χ	Χ
	REF	Comr	nand		0 = Off in Standby 1 = On in Standby	00 = 01 = 10 =	Mode: EXT 2.5V 2.0V 4.0V				Don't	Care							Don't	Care			
	Defau	lt Valu	ues →	•	0	0	0	Χ	Χ	Χ	X	Χ	Χ	Χ	Χ	Χ	X	Χ	Χ	X	Χ	Χ	Х

## Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

## **Applications Information**

### Power-On Reset (POR)

When power is applied to  $V_{DD}$  and  $V_{DDIO}$ , the DAC output is set to zero scale. To optimize DAC linearity, wait until the supplies have settled and the internal setup and calibration sequence completes (200 $\mu$ s, typ).

### Power Supplies and Bypassing Considerations

Bypass  $V_{DD}$  and  $V_{DDIO}$  with high-quality ceramic capacitors to a low-impedance ground as close as possible to the device. Minimize lead lengths to reduce lead inductance. Connect the GND to the analog ground plane.

#### **Layout Considerations**

Digital and AC transient signals on GND can create noise at the output. Connect GND to form the star ground for the DAC system. Refer remote DAC loads to this system ground for the best possible performance. Use proper grounding techniques, such as a multilayer board with a low-inductance ground plane, or star connect all ground return paths back to the MAX5700/MAX5701/MAX5702 GND. Carefully layout the traces between channels to reduce AC cross-coupling. Do not use wire-wrapped boards and sockets. Use shielding to minimize noise immunity. Do not run analog and digital signals parallel to one another, especially clock signals. Avoid routing digital lines underneath the MAX5700/MAX5701/MAX5702 package.

#### **Definitions**

#### Integral Nonlinearity (INL)

INL is the deviation of the measured transfer function from a straight line drawn between two codes once offset and gain errors have been nullified.

#### **Differential Nonlinearity (DNL)**

DNL is the difference between an actual step height and the ideal value of 1 LSB. If the magnitude of the DNL  $\leq$  1 LSB, the DAC guarantees no missing codes and is monotonic. If the magnitude of the DNL  $\geq$  1 LSB, the DAC output may still be monotonic.

#### Offset Error

Offset error indicates how well the actual transfer function matches the ideal transfer function. The offset error is calculated from two measurements near zero code and near maximum code.

#### **Gain Error**

Gain error is the difference between the ideal and the actual full-scale output voltage on the transfer curve, after nullifying the offset error. This error alters the slope of the transfer function and corresponds to the same percentage error in each step.

#### Zero-Scale Error

Zero-scale error is the difference between the DAC output voltage when set to code zero and ground. This includes offset and other die level nonidealities.

#### Full-Scale Error

Full-scale error is the difference between the DAC output voltage when set to full scale and the reference voltage. This includes offset, gain error, and other die level nonidealities.

#### **Settling Time**

The settling time is the amount of time required from the start of a transition, until the DAC output settles to the new output value within the converter's specified accuracy.

#### **Digital Feedthrough**

Digital feedthrough is the amount of noise that appears on the DAC output when the DAC digital control lines are toggled.

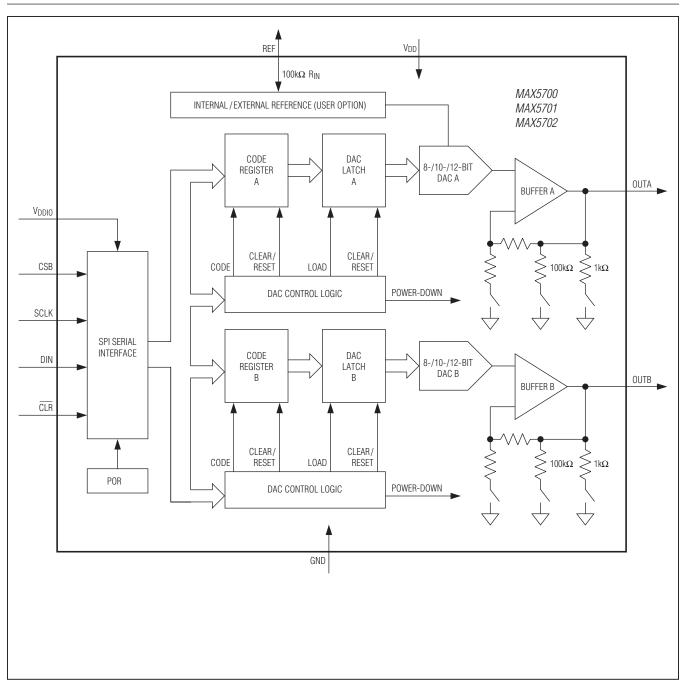
#### **Digital-to-Analog Glitch Impulse**

A major carry transition occurs at the midscale point where the MSB changes from low to high and all other bits change from high to low, or where the MSB changes from high to low and all other bits change from low to high. The duration of the magnitude of the switching glitch during a major carry transition is referred to as the digital-to-analog glitch impulse.

The digital-to-analog power-up glitch is the duration of the magnitude of the switching glitch that occurs as the device exits power-down mode.

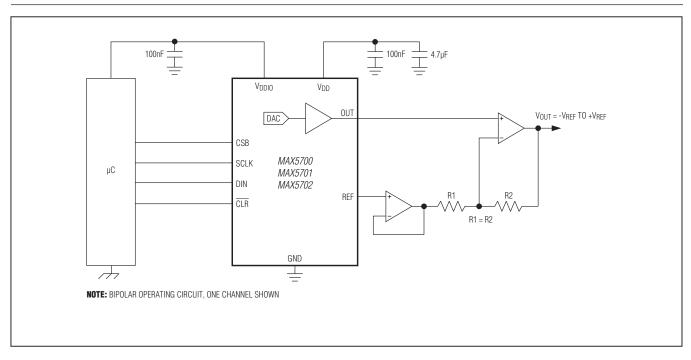
# Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

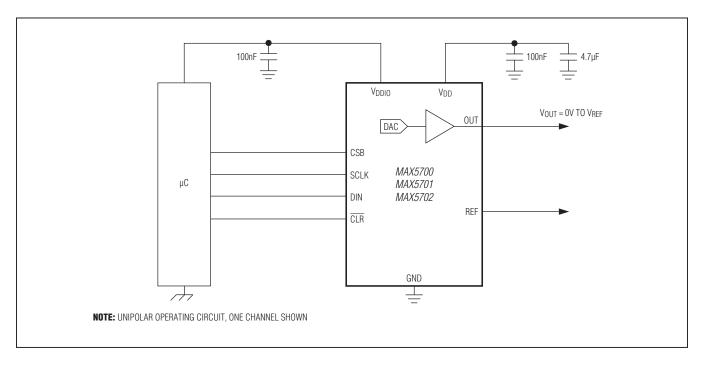
**Detailed Functional Diagram** 



# Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

**Typical Operating Circuits** 





# Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

## **Ordering Information**

10 (typ), 25 (max) 10 (typ), 25 (max)
10 (typ), 25 (max)
(317)
10 (typ), 25 (max)
10 (typ), 25 (max)
3 (typ), 10 (max)
3 (typ), 10 (max)
10 (typ), 25 (max)
10 (typ), 25 (max)

**Note:** All devices are specified over the -40°C to +125°C temperature range.

### **Chip Information**

### **Package Information**

PROCESS: BiCMOS

For the latest package outline information and land patterns (footprints), go to <a href="https://www.maximintegrated.com/packages">www.maximintegrated.com/packages</a>. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
10 μMAX	U10+2	<u>21-0061</u>	90-0330
10 TDFN-EP	T1033+1	21-0137	90-0003

but the drawing pertain status.

<sup>+</sup>Denotes a lead(Pb)-free/RoHS-compliant package.

T = Tape and reel.

<sup>\*</sup>Future product—Contact factory for availability.

<sup>\*\*</sup>EP = Exposed pad.

# Ultra-Small, Dual-Channel, 8-/10-/12-Bit Buffered Output DACs with Internal Reference and SPI Interface

### **Revision History**

REVISION	REVISION	DESCRIPTION	PAGES
NUMBER	DATE		CHANGED
0	9/12	Initial release	_



Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time. The parametric values (min and max limits) shown in the Electrical Characteristics table are guaranteed. Other parametric values quoted in this data sheet are provided for guidance.